

Preliminary ABRIDGED APPROVAL FORM - Hercrom400G2C035 -

Originator: Michel Gac

	Approval	Approval	Approval	Approval	Approval
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Signature					

HISTORY

Version	Date	Author	Approval managers	Approval date	Notes
Ver: 0.1	06/24/02	Rodolphe Servato	Michel Gac	06/24/02	1
Ver 0.2	07/24/02	Rodolphe Servato	Michel Gac	07/24/02	2

NOTES :

1. Document creation from CAL000_A C035 v0.9.
2. Remove Memory interface timing table (I/O MIF supply voltage 1.90 -> 2.1 V).

3.

a) *General informations:*

Parameter	Description			
Technology	1533C035			
Library	GS40			
F number	F751774			
Baset	BF751774			
Packaging <i>U*BGA</i>	Qualified	Package id	Substrate (EIS)	Application
	<i>No</i>	<i>GHH179</i>		<i>Prod</i>
DSP ROM code	V3416			
BOOT ROM code	V0300			
ROM protection	Y			



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b) DC Parameters:

Parameter	Description	Note	Min	Typ	Max	Unit
T _A	Operating temperature	Free air	-40	-	85	°C
VDDS-1	I/O Supply Voltage	Level_shifter	2.5	2.8	3	V
VDDS-2	I/O Supply Voltage	Level_shifter	2.5	2.8	3	V
VDDS-MIF	I/O MIF Supply Voltage	Level_shifter	1.65	2.8	3	V
VDDS-RTC	I/O RTC Supply Voltage	Level_shifter	1.35	2.8	3	V
VDDANG	Analog Supply Voltage		2.5	2.8	3	V
VDDPLL	DPLL Supply Voltage		1.35	1.5	1.65	V
VDD	Core logic Supply Voltage		1.35	1.5	1.65	V
VDD-RTC	RTC logic Supply Voltage		1.35	1.5	1.65	V
Vih	High-level input voltage	Level_shifter	0.7*VDDS ^[1]	-	VDDS+0.5	V
Vil	Low-level input voltage	Level_shifter	-0.5	-	0.3*VDDS	V
Voh	High-level output voltage	rated current	0.8*VDDS	-		V
Vol	Low-level output voltage	rated current			0.22*VDDS	V
Iol/Ioh	Rated output current	Level_shifter		-		
	Type1	Voh=VCC _{Min} ^[1]		-	1	mA
		Vol= VCC _{Max} ^[1]			1	mA
	Type2	Voh=VCC _{Min} ^[1]		-	2	mA
		Vol= VCC _{Max} ^[1]			2	mA
	Type3	Voh=VCC _{Min} ^[1]		-	4	mA
Vol= VCC _{Max} ^[1]				4	mA	
Iil/Iih	Input leakage current		-1	-	1	uA
Iozl/Iozh	High-Z Output leakage current		-20	-	20	uA

[1] See list of Type1, Type2 and Type3 pins in annex.

c) AC Parameters:

Core Parameters

Parameter	Description	Note	Min	Typ	Max	Unit
ARM7 F _{cyc}	cycle frequency		0	-	52	MHz
C28L128 F _{cycl}	cycle frequency		0	-	104	MHz

Oscillator parameters

Parameter	Description	Note	Min	Typ	Max	Unit
OSC32K	Oscillator input frequency	Sinus inp. [4] [5]		32.768		KHz

[4] http://www.asic.sc.ti.com/~adocs/g40_aug01/docs/mls/oscillator/os11h1.htm

[5] nominal value according to crystal manufacturer with recommended value for external components

VTCXO general parameters

Parameter	Description	Note	Min	Typ	Max	Unit
CLKTCXO	Input frequency	[4]	13		26	MHz
	Input precision		-12		+12	ppm
	Input amplitude (AC)	[4]	0.5	1	2	V
	Input Impedance	R _{in}		20	30	65
C _{in}			6.45	5.85	5	pF

[4] http://www.asic.sc.ti.com/~adocs/g40_aug01/docs/mls/analog/ck321.htm

VTCXO @13Mhz paramters

Parameter	Description	Note	Min	Typ	Max	Unit
CLKTCXO	Duty cycle		45	50	55	%
	Jitter	1V amplitude			300	Ps

[4] http://www.asic.sc.ti.com/~adocs/g40_aug01/docs/mls/analog/ck321.htm

VTCXO @26Mhz paramters

Parameter	Description	Note	Min	Typ	Max	Unit
CLKTCXO	Duty cycle		40	50	60	%
	Jitter	1V amplitude			300	Ps

[4] http://www.asic.sc.ti.com/~adocs/g40_aug01/docs/mls/analog/ck321.htm

32KHz quartz connection

For Details refers to Document:

- 32KHz oscillator PCB recommendation and layout guidelines.
- APN0 (Calypso/Iota/Clara System Application Note)



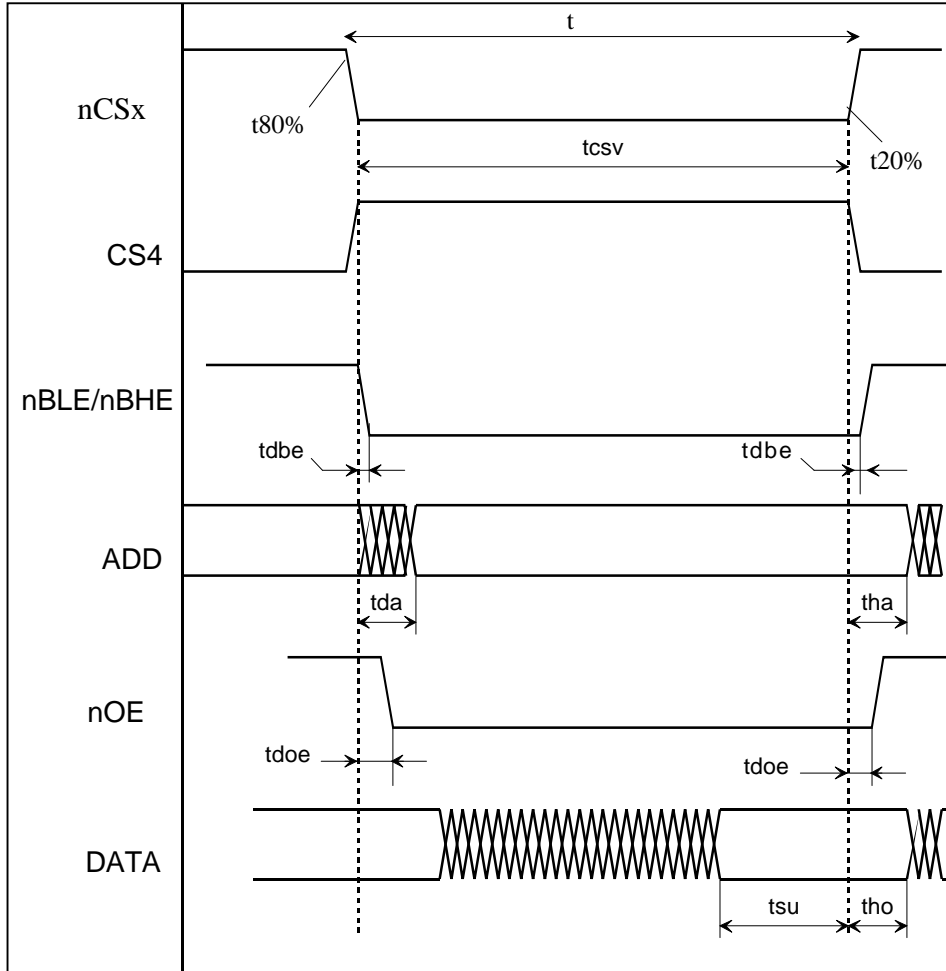
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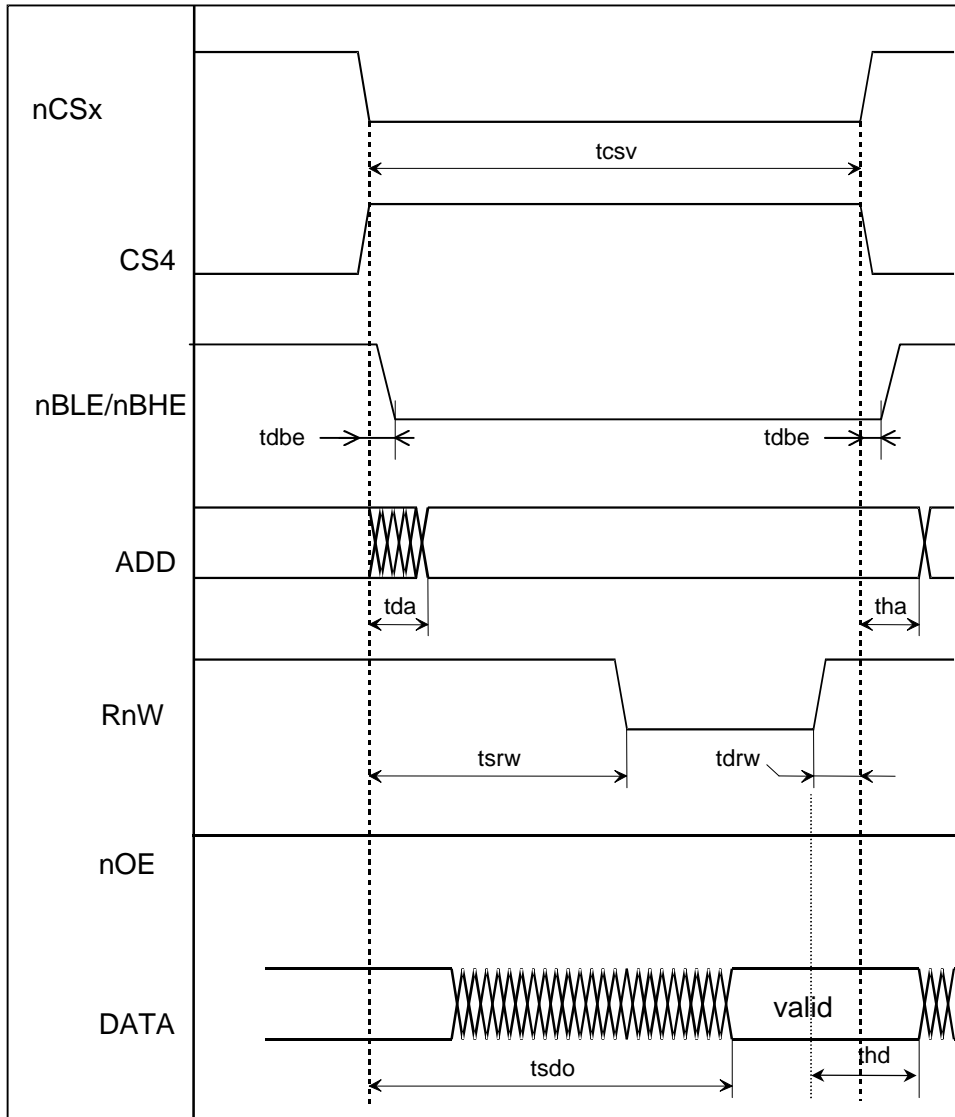
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Read access timing



Write access timing



Memory interface timing table (I/O MIF supply voltage 2.5 -> 3 V)

Name	Function	Min	Max
tcyc	MCU input frequency	-	19.23 ns (52.0 Mhz)
N	Number of wait state	0	31

Name	Function	Min (ns)	Max (ns)
tcsv	Chip Select valid	$tcyc$	$(N + 1) \times tcyc$
tda	nCS \ to Address valid	-	5.9
tha	Address hold from nCS /	0	-
tdbe	NBHE, nBLE \ to nCS \	-	0.2
tdoe	nOE \ to nCS \	-	0.5
tsu	Input data setup to nCS /	4.6	-
tho	Input data hold from nCS /	0	-
tsrw	nCS \ to RnW \	$\frac{tcyc}{2} - tdrw$	-
tdrw	RnW / to nCS /	0.9	2.1
tdso	nCS \ to output data valid	-	$(tsrw + 7)$
thd	Output data hold from RnW /	0.7	-

Note: all timings computed for an external capacitance load of 20pF.

For larger load capacitance CL then compute timings from table,

$$T_{CL} = T_{20pF} + 0.08nS/pF * (CL - 20pF) \text{ with } CL \text{ Max} = 50pF$$

Memory interface timing table (I/O MIF supply voltage 1.65 -> 1.95 V)*:

Name	Function	Min	Max
tcyc	MCU input frequency	-	19.23 ns (52.0 Mhz)
tclk	Internal Mclk \ to nCS /	-	11
N	Number of wait state	0	31

Name	Function	Min (ns)	Max (ns)
tcsv	Chip Select valid	<i>tcyc</i>	$(N + 1) \times tcyc$
tda	nCS \ to Address valid	-	3.4
tha	Address hold from nCS /	0.5	-
tdbe	nBHE, nBLE \ to nCS \	-	0.2
tdoe	nOE \ to nCS \	-	0.3
tsu	Input data setup to nCS /	4.5	-
tho	Input data hold from nCS /	0	-
tsrw	nCS \ to RnW \	$\frac{tcyc}{2} - tdrw$	-
tdrw	RnW / to nCS /	0.9	2.3
tdso	nCS \ to output data valid	-	$(tsrw + 7)$
thd	Output data hold from RnW /	0.2	-

Note: all timings computed for an external capacitance load of 20pF.

For larger load capacitance CL then compute timings from table,

$$T_{CL} = T_{20pF} + 0.08nS/pF * (CL - 20pF) \text{ with } CL \text{ Max} = 30pF$$

*For using 1.65V external memory on CALYPSO with IOTA ABB see CAL000.doc for connection with IOTA

NOTE: nCS4 can't be use with this supply voltage

External memory access time vs MCU clock (examples)

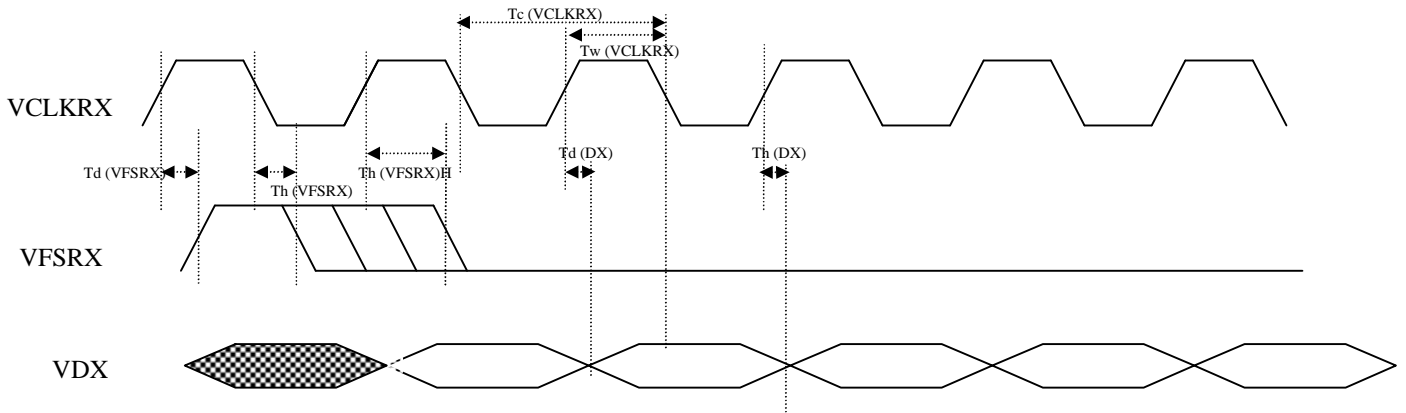
The formula for to calculate access time is in our case:

$$(t_{csv} - t_{su} - t_{da}) = T_{acc} \quad (N + 1) \times t_{cyc} - t_{su} - t_{da} = T_{acc}$$

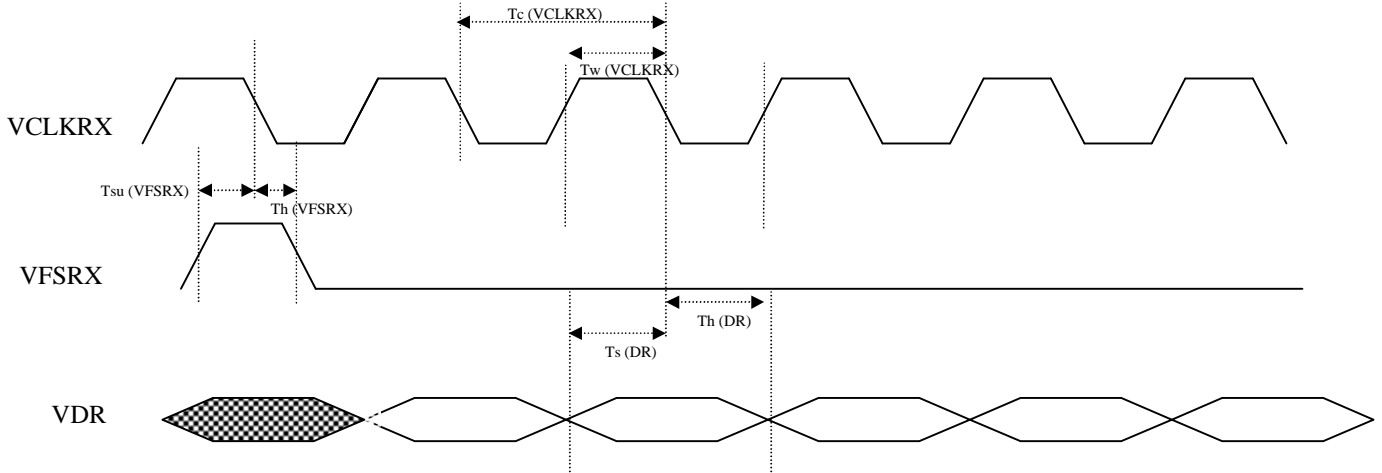
So the results for following example values are:

MCU Clock (Mhz)	2.5V ->3V		1.9V -> 2.1V		1.65V ->1.9V	
	Tacc 0 ws (ns)	Tacc 1 ws (ns)	Tacc 0 ws (ns)	Tacc 1 ws (ns)	Tacc 0 ws (ns)	Tacc 1 ws (ns)
6.5	145.9462	299.7923	144.5462	298.3923	143.3462	297.1923
13	69.02308	145.9462	67.62308	144.5462	66.42308	143.3462
19.5	43.38205	94.6641	41.98205	93.2641	40.78205	92.0641
26	30.56154	69.02308	29.16154	67.62308	27.96154	66.42308
32.5	22.86923	53.63846	21.46923	52.23846	20.26923	51.03846
39	17.74103	43.38205	16.34103	41.98205	15.14103	40.78205
45.5	14.07802	36.05604	12.67802	34.65604	11.47802	33.45604
52	11.33077	30.56154	9.930769	29.16154	8.730769	27.96154

Serial port transmit timing



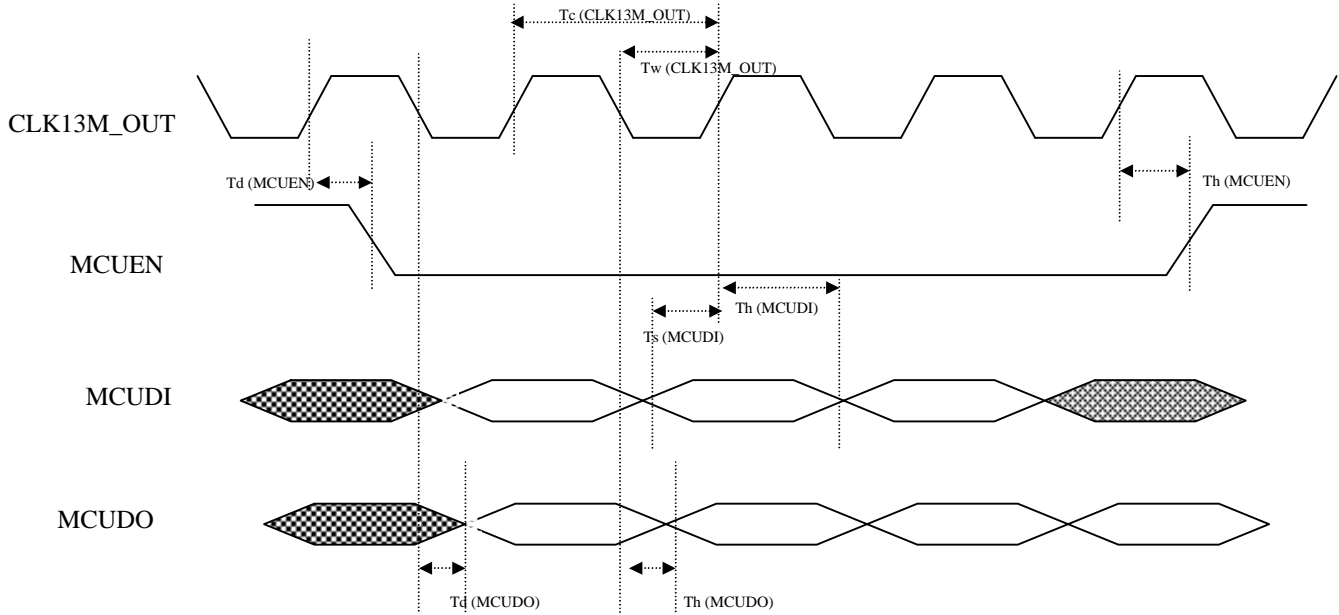
Serial port receive timing



SPI timing table

Parameter	Min	Max	Unit
T : cDSP clock period	10.99		Ns
Tw(VCLKRX) Pulse duration, serial port clock	3T		Ns
Tc(VCLKRX) Cycle time, serial port clock	6T		Ns
Td (DX) Delay time, Data valid after VCLKRX rising		25	Ns
Th(DX) Hold time, Data valid after VCLKRX rising	-5		Ns
Td(VFSRX) Delay time, VFSRX after VCLKRX rising edge		T+5	Ns
Th(VFSRX) Hold time, VFSRX after VCLKRX falling edge	10		Ns
Th(VFSRX)H hold time, VFSRX after VCLKRX rising edge		T+5	ns
Ts (DR) Setup, Data valid after VCLKRX rising	15		ns
Th(DR) Hold time, Data valid after VCLKRX rising	10		Ns
Tsu(VFSRX) Setup time, VFSRX before VCLKRX falling edge	15		Ns

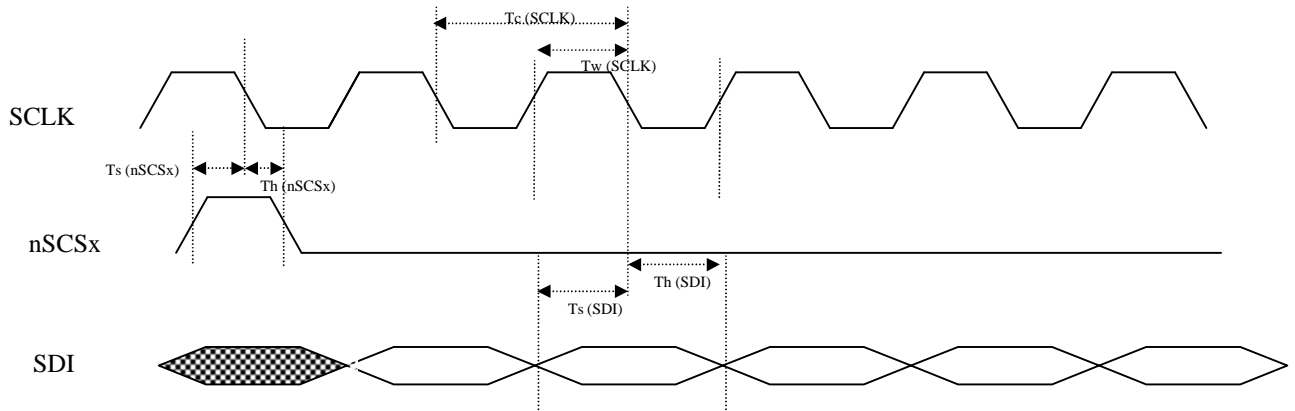
ARM Serial port



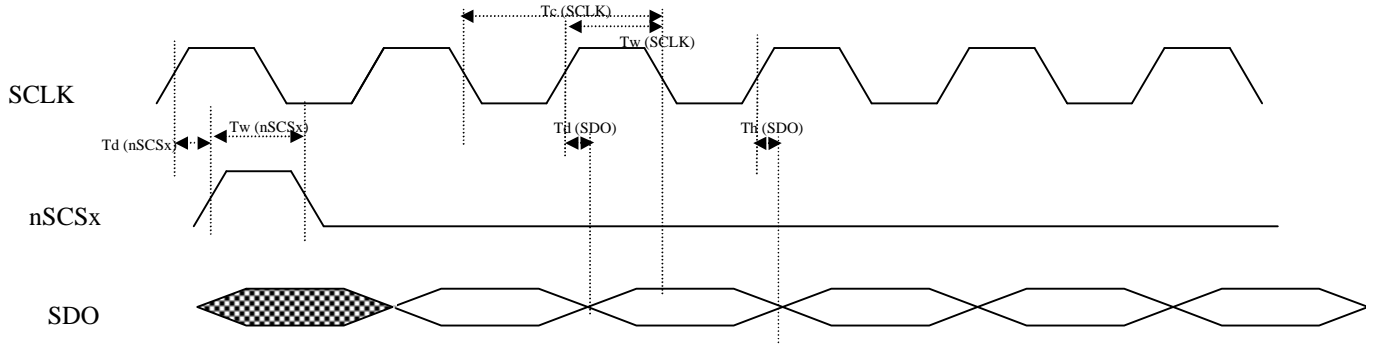
ARM Serial port timing table

Parameter	Min	Max	Unit
$T_w(\text{CLK13M_OUT})$ Pulse duration, serial port clock	38		Ns
$T_c(\text{CLK13M_OUT})$ Cycle time, serial port clock	77		Ns
$T_d(\text{MCUDO})$ Delay time, Data valid after CLK falling		8.2	Ns
$T_h(\text{MCUDO})$ Hold time, Data valid after CLK falling	0		Ns
$T_d(\text{MCUEN})$ Delay time, EN after CLK rising edge		7.5	Ns
$T_h(\text{MCUEN})$ Hold time, EN after CLK rising edge	0		Ns
$T_s(\text{MCUDI})$ Setup, Data valid before CLK rising	7.5		Ns
$T_h(\text{MCUDI})$ Hold time, Data valid after CLK rising	2.5		Ns

MICROWIRE port receive timing



MICROWIRE port transmit timing



MICROWIRE port timing table

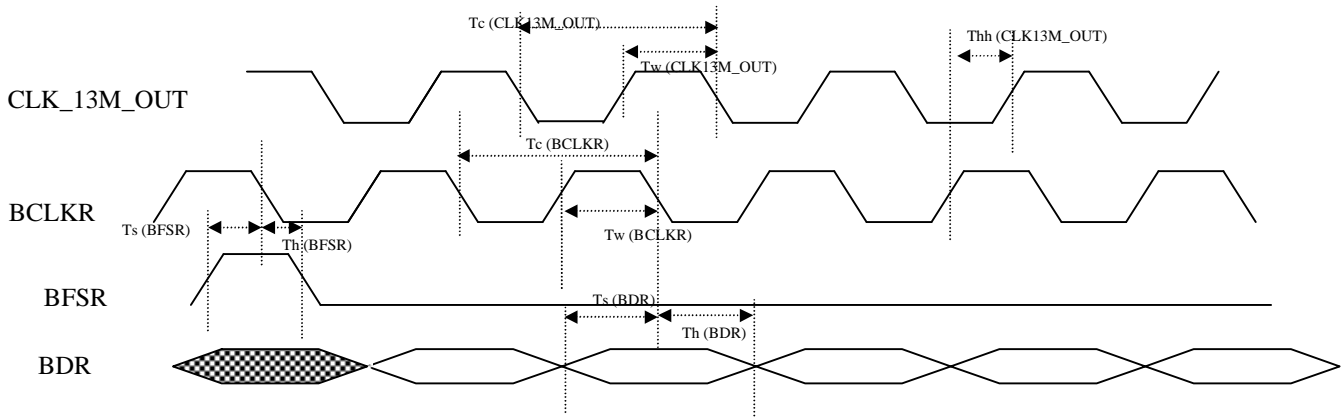
Parameter	Min	Max	Unit
Tw(SCLK) Pulse duration, serial port clock	154	*	Ns
Tc(SCLK) Cycle time, serial port clock	308	*	Ns

Td(SDO) Delay time, Data valid after CLK rising		10	Ns
Th(SDO) Hold time, Data valid after CLK rising	0		Ns
Tw(nSCSx) Pulse duration, EN port	154		Ns
Td(nSCSx) Delay time, EN after CLK rising edge		10	Ns

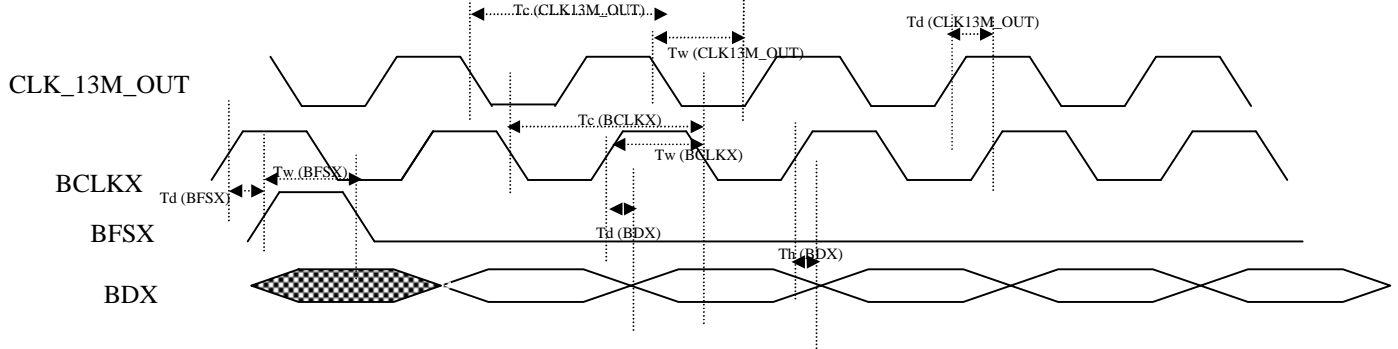
Ts(SDI) Setup, Data valid before CLK falling	15		Ns
Th(SDI) Hold time, Data valid after CLK falling	15		Ns
Ts(nSCSx) setup time, EN before CLK falling edge	10		Ns
Th(nSCSx) Hold time, EN after CLK falling edge	10		Ns

*depending on peripheral Register programming

Base Band Interface port receive timing



Base Band Interface port transmit timing



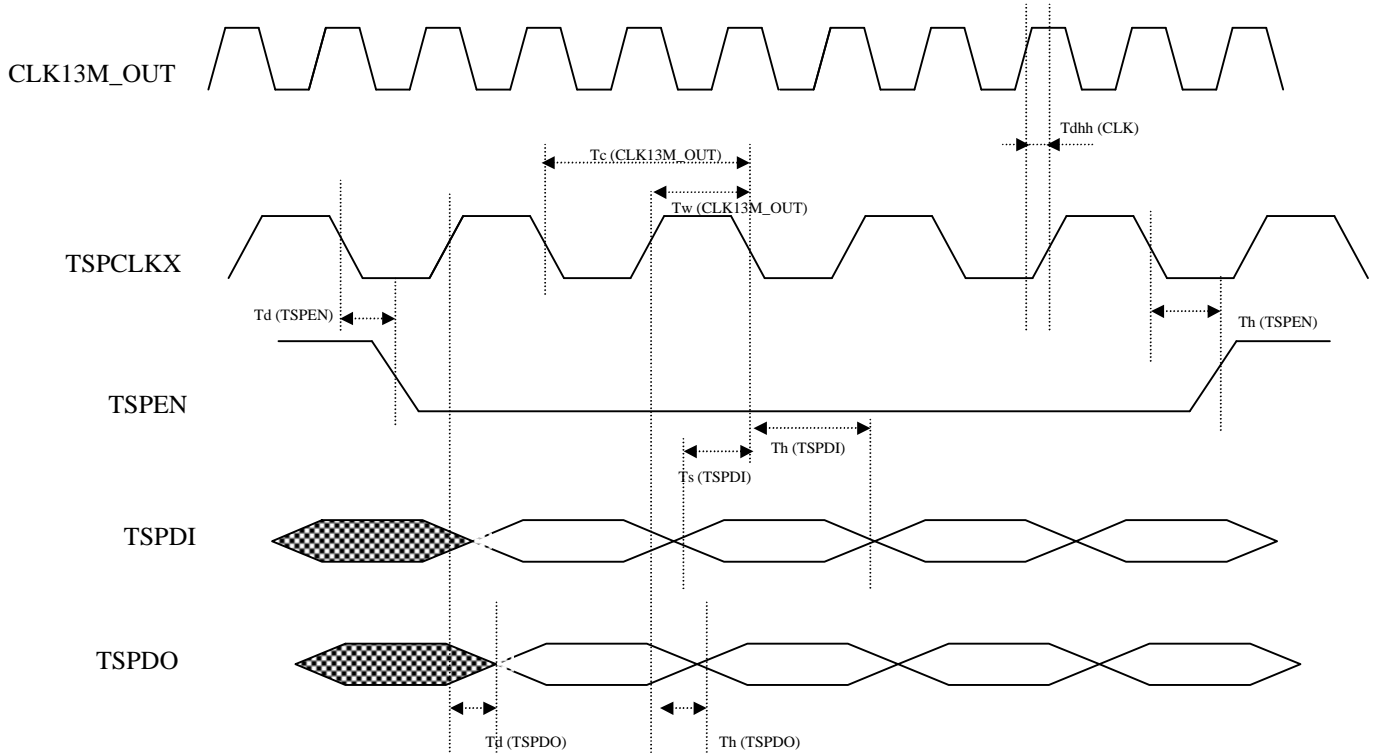
Base Band Interface port timing table

Parameter	Min	Max	Unit
Tw(BCLKR) Pulse duration, serial port clock	38	*	Ns
Tc(BCLKR) Cycle time, serial port clock	77	*	Ns
Tc(CLK_13M_OUT) Cycle time	77		Ns
Td(CLK_13M_OUT) Delay time		5.0	Ns
Thh(CLK_13M_OUT) Delay time**		3.2	Ns
** CLK_13M_OUT after BCLKR_INT			
Ts(BDR) Setup, Data valid before CLK falling	15		Ns
Th(BDR) Hold time, Data valid after CLK falling	8		Ns
Ts(BFSR) setup time, EN before CLK falling edge	10		Ns
Th(BFSR) Hold time, EN after CLK falling edge	8		Ns
Tw(BCLKX) Pulse duration, serial port clock	38	*	Ns
Tc(BCLKX) Cycle time, serial port clock	77	*	Ns
Td(BDX) Delay time, Data valid after CLK rising		12	Ns
Th(BDX) Hold time, Data valid after CLK rising	0		Ns
Td(BFSX) Delay time, EN after CLK rising edge		10	Ns
Tw(BFSX) Pulse duration, EN port	38		Ns

*depending on peripheral Register programming



TPU serial port

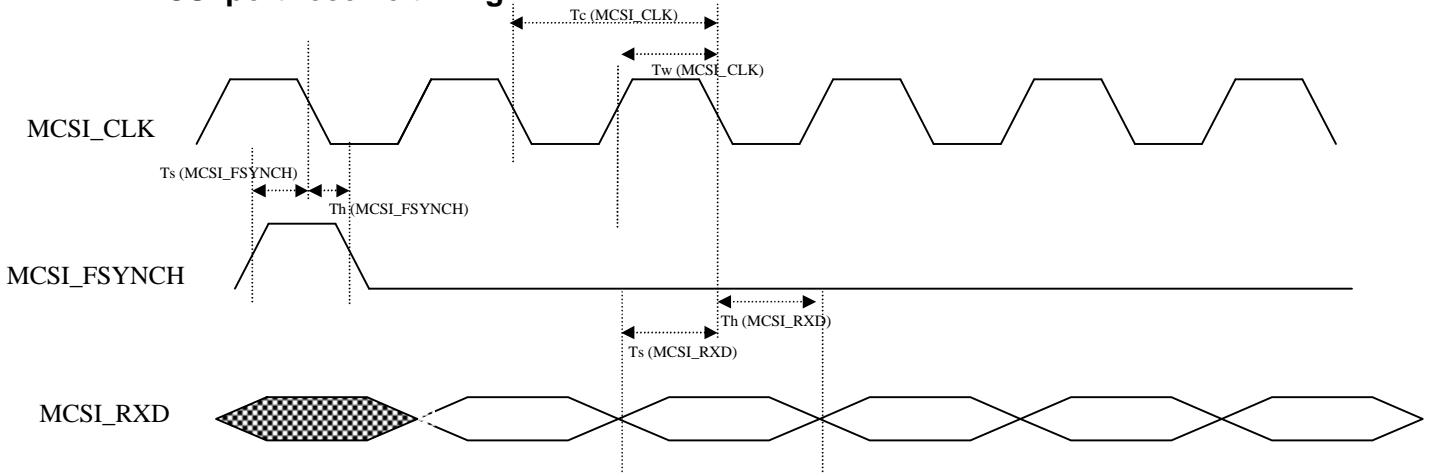


TPU serial port timing table

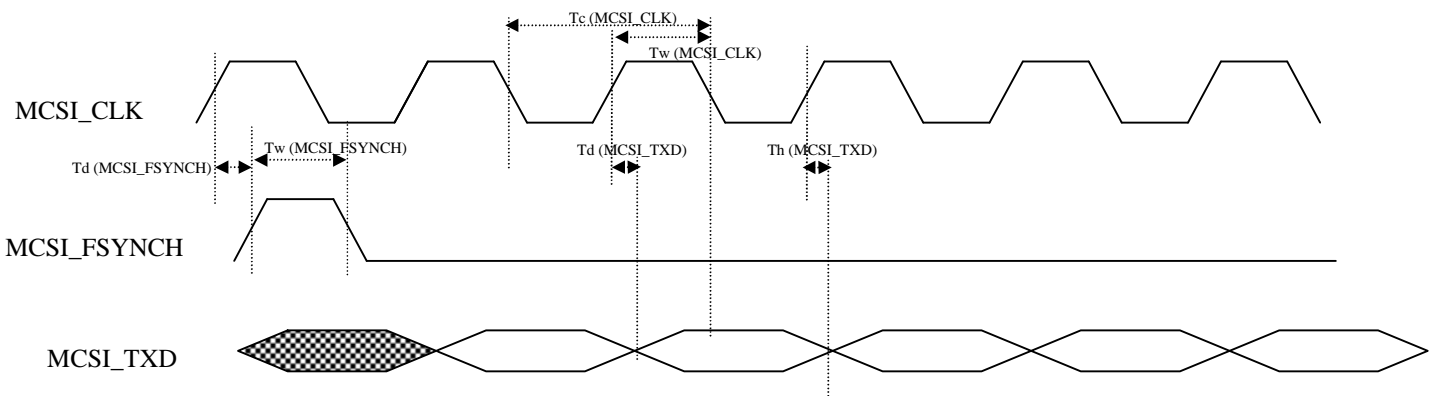
Parameter	Min	Max	Unit
T_w (TSPCLKX) Pulse duration, serial port clock	77	*	Ns
T_c (TSPCLKX) Cycle time, serial port clock	154	*	Ns
T_{dhh} (CLK) Delay time, TSPCLKX rising after CLK_13M_OUT rising		0.9	Ns
T_d (TSPDO) Delay time, Data valid after CLK rising		10	Ns
T_h (TSPDO) Hold time, Data valid after CLK rising	0		Ns
T_s (TSPDI) Setup, Data valid before CLK falling	15		Ns
T_h (TSPDI) Hold time, Data valid after CLK falling	15		Ns
T_d (TSPEN) Delay time, EN after CLK falling edge		10	Ns
T_h (TSPEN) Hold time, EN after CLK falling edge	0		Ns

*depending on peripheral Register programming

MCSI port receive timing



MCSI port transmit timing

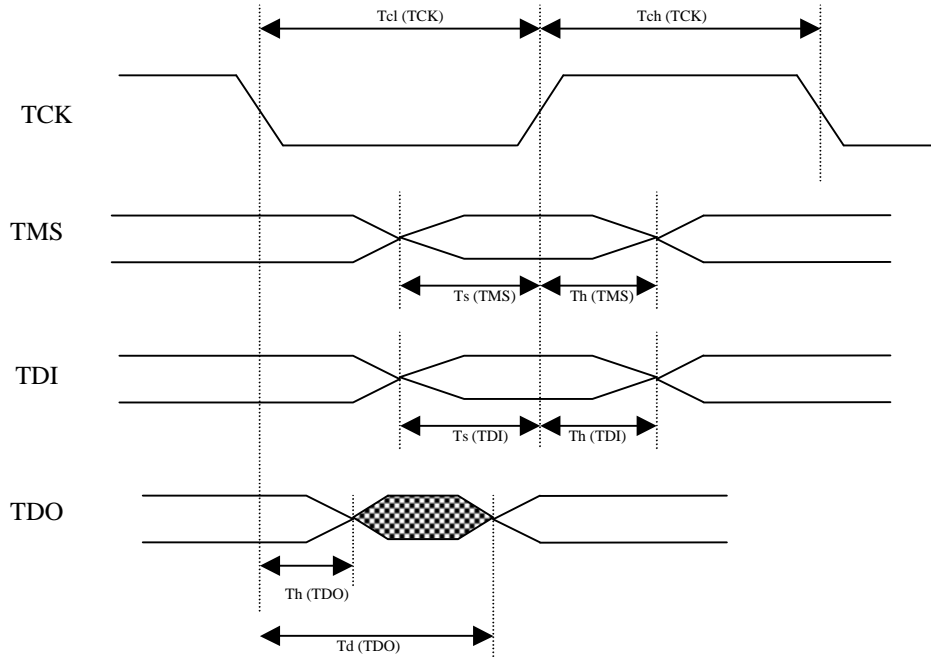


MCSI port timing table

Parameter	Min	Max	Unit
Tw(MCSI_CLK) Pulse duration, serial port clock	77	*	Ns
Tc(MCSI_CLK) Cycle time, serial port clock	154	*	Ns
Td (MCSI_TXD) Delay time, Data valid after CLK rising		10	Ns
Th(MCSI_TXD) Hold time, Data valid after CLK rising	0		Ns
Td(MCSI_FSYNCH) Delay time, EN after CLK rising edge		10	Ns
Tw(MCSI_FSYNCH) Pulse duration, EN port	77		Ns
Ts (MCSI_RXD) Setup, Data valid before CLK falling	15		Ns
Th(MCSI_RXD) Hold time, Data valid after CLK falling	15		Ns
Ts(MCSI_FSYNCH) setup time, EN before CLK falling edge	10		Ns
Th(MCSI_FSYNCH) Hold time, EN after CLK falling edge	10		Ns

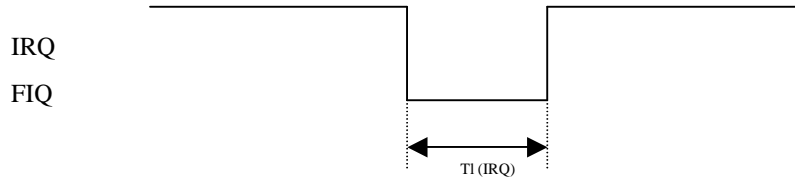
*depending on peripheral Register programming

JTAG interface



Parameter	Min	Max	Unit
$T_{cl}(TCK)$ TCK low period	50		Ns
$T_{ch}(TCK)$ TCK high period	50		Ns
$T_s(TMS)$ Setup time TMS	15		Ns
$T_h(TMS)$ Hold time TMS	15		Ns
$T_s(TDI)$ Setup time TMS	15		Ns
$T_h(TDI)$ Hold time TMS	15		Ns
$T_d(TDO)$ Delay time valid TDO		25	Ns
$T_h(TDO)$ Hold time TDO	0		Ns

Interrupt



Parameter	Min	Max	Unit
TI(IRQ) Pulse duration in functional mode	77		Ns

ANNEXE 1

Level shifter Type 1 : OUO231

Level shifter Type 2 : OUI431, OUK 431, OUO431

Level shifter Type 3 : OUI831, OUK831

